

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111  
Serial Number: 09/726,629  
Filing Date: November 30, 2000  
Title: SOLDERLESS ELECTRONICS PACKAGING (as amended)  
Assignee: Intel Corporation

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### IN THE CLAIMS

Please amend the claims as follows:

Claims 1-34 (Cancelled)

35. (Currently Amended) An electronic package comprising:  
a die;  
a substrate; and  
a compressible connector to couple the die to the substrate, wherin the connector includes  
a flexible support formed of plastic, and  
a plurality of elements formed of electrically conductive material, the elements being from the group consisting of wire wads, pins, blobs, lumps, particles, and crystals.

36. (Currently Amended) The electronic package recited in claim 35, wherein the connector comprises a plurality of electrically conductive elements are to couple lands on the die to corresponding lands on the substrate.

37. (Original) The electronic package recited in claim 36 and further comprising:  
a compression element to maintain electrical contact between the lands on the die and the lands on the substrate.

38. (Original) The electronic package recited in claim 37, wherein the compression element is a lid comprising a member in contact with the die and a support coupled to the substrate.

39. (Currently Amended) The electronic package recited in claim 35 36, wherein the electrically conductive elements comprise a compressible material.

Claims 40-41 (Cancelled)

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42. (Currently Amended) The electronic package recited in claim 35 -41, wherein the elements comprise a coating of electrically conductive material.

43. (Currently Amended) The electronic package recited in claim 35 -40, wherein the plurality of elements comprise material from the group consisting of aluminum, antimony, beryllium, bismuth, cadmium, carbon, chromium, copper, gold, indium, iron, lead, magnesium, manganese, molybdenum, nickel, palladium, platinum, silicon, silver, tin, titanium, tungsten, zinc, metal silicide, doped polysilicon, and plastic.

44. (Currently Amended) An electronic package comprising:  
an integrated circuit (IC) package;  
a substrate; and  
a compressible connector to couple the IC package to the substrate, wherein the connector includes  
a flexible support formed of plastic, and  
a plurality of elements formed of electrically conductive material, the elements being from the group consisting of wire wads, pins, blobs, lumps, particles, and crystals.

45. (Currently Amended) The electronic package recited in claim 44, wherein the connector comprises a plurality of electrically conductive elements are to couple lands on the IC package to corresponding lands on the substrate.

46. (Original) The electronic package recited in claim 45 and further comprising:  
a compression element to maintain electrical contact between the lands on the IC package and the lands on the substrate.

47. (Original) The electronic package recited in claim 46, wherein the compression element is a lid comprising a member in contact with the IC package and a support coupled to the substrate.

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48. (Currently Amended) The electronic package recited in claim 44 -45, wherein the ~~electrically conductive~~ elements comprise a compressible material.

Claims 49-50 (Canceled)

51. (Currently Amended) The electronic package recited in claim 44 50, wherein the elements comprise a coating of electrically conductive material.

52. (Currently Amended) The electronic package recited in claim 44 49, wherein the plurality of elements comprise material from the group consisting of aluminum, antimony, beryllium, bismuth, cadmium, carbon, chromium, copper, gold, indium, iron, lead, magnesium, manganese, molybdenum, nickel, palladium, platinum, silicon, silver, tin, titanium, tungsten, zinc, metal silicide, doped polysilicon, and plastic.

53. (Currently Amended) An electronic system comprising at least one electronic assembly comprising:

an integrated circuit (IC) package;

a substrate; and

a compressible connector to couple the IC package to the substrate, wherein the connector includes

a flexible support formed of plastic, and

a plurality of elements formed of electrically conductive material, the elements being from the group consisting of wire wads, pins, blobs, lumps, particles, and crystals.

54. (Currently Amended) The electronic system recited in claim 53, wherein the connector comprises a plurality of electrically conductive elements are to couple lands on the IC package to corresponding lands on the substrate.

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55. (Original) The electronic system recited in claim 54, wherein the at least one electronic assembly further comprises a compression element to maintain electrical contact between the lands on the IC package and the lands on the substrate.

56. (Currently Amended) A data processing system comprising:

a bus coupling components in the data processing system;

a display coupled to the bus;

external memory coupled to the bus; and

a processor coupled to the bus and including at least one electronic assembly that includes comprising:

an integrated circuit (IC) package;

a substrate; and

a compressible connector to couple the IC package to the substrate, wherein the connector includes

a flexible support formed of plastic, and

a plurality of elements formed of electrically conductive material, the

elements being from the group consisting of wire wads, pins, blobs, lumps,

particles, and crystals.

57. (Currently Amended) The data processing system recited in claim 56, wherein the connector comprises a plurality of electrically conductive elements are to couple lands on the IC package to corresponding lands on the substrate.

58. (Original) The data processing system recited in claim 57, wherein the at least one electronic assembly further comprises a compression element to maintain electrical contact between the lands on the IC package and the lands on the substrate.

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Please add new claims 59-72 as follows:

59. (New) An electronic package comprising:  
a die;  
a substrate; and  
a compressible connector to couple the die to the substrate, wherein the connector includes a flexible insulating support and a plurality of wire wads.

60. (New) The electronic package recited in claim 59, wherein the plurality of wire wads are to couple lands on the die to corresponding lands on the substrate.

61. (New) The electronic package recited in claim 60 and further comprising a compression element to maintain electrical contact between the lands on the die and the lands on the substrate.

62. (New) The electronic package recited in claim 61, wherein the compression element is a lid comprising a member in contact with the die and a support coupled to the substrate.

63. (New) The electronic package recited in claim 59, wherein the wire wads comprise a compressible material.

64. (New) The electronic package recited in claim 59, wherein the insulating support is formed of material from the group consisting of a plastic, a resin, and a polymer.

65. (New) An electronic package comprising:  
an integrated circuit (IC) package;  
a substrate; and  
a compressible connector to couple the IC package to the substrate, wherein the connector includes a flexible insulating support and a plurality of wire wads.

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66. (New) The electronic package recited in claim 65, wherein the plurality of wire wads are to couple lands on the IC package to corresponding lands on the substrate.

67. (New) The electronic package recited in claim 66 and further comprising a compression element to maintain electrical contact between the lands on the IC package and the lands on the substrate.

68. (New) The electronic package recited in claim 65, wherein the insulating support is formed of material from the group consisting of a plastic, a resin, and a polymer.

69. (New) An electronic system comprising at least one electronic assembly comprising:  
an integrated circuit (IC) package;  
a substrate; and  
a compressible connector to couple the IC package to the substrate, wherein the connector includes a flexible insulating support and a plurality of wire wads.

70. (New) The electronic system recited in claim 69, wherein the plurality of wire wads are to couple lands on the IC package to corresponding lands on the substrate.

71. (New) The electronic package recited in claim 70 and further comprising a compression element to maintain electrical contact between the lands on the IC package and the lands on the substrate.

72. (New) The electronic package recited in claim 69, wherein the insulating support is formed of material from the group consisting of a plastic, a resin, and a polymer.